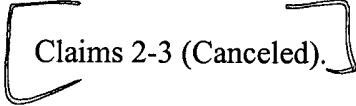



IN THE CLAIMS

1 (Currently Amended). A method comprising:
coupling a first and second surface of an electronic device in spaced apart relationship so as to form a region between said first and second surfaces; and
forming a centrally located hole in one of said surfaces;
forming a plurality of radially displaced holes arranged at a substantially uniform radius from said centrally located hole; and
injecting an encapsulant between said first and second surfaces through one of said holes surfaces.

 Claims 2-3 (Canceled).

 4 (Currently Amended). The method of claim 1 3 including injecting encapsulant through said centrally located hole until the encapsulant reaches said radially displaced holes and thereafter stopping the injection of encapsulant through said centrally located hole and injecting encapsulant through said radially displaced holes.

5 (Original). The method of claim 1 wherein injecting an encapsulant includes causing an encapsulant front to extend outwardly from the center of a region to be encapsulated between said first and second surfaces.

6 (Original). The method of claim 5 including injecting encapsulant through a central hole through one of said surfaces.

7 (Original). The method of claim 6 including terminating the injection of encapsulant through said central hole and injecting encapsulant through a plurality of holes substantially uniformly radially displaced with respect to said central hole.

8 (Original). The method of claim 7 including stopping the injection of said encapsulant through radially displaced holes and initiating the injection of encapsulant through a second set of holes radially displaced with respect to said radially displaced holes.

9 (Original). The method of claim 1 including forming an electronic display.

[Claim 10 (Canceled).]

11 (Currently Amended). An electronic device comprising:
a first surface;
a second surface spaced from said first surface, ~~said second surface including at least one encapsulation injection port extending through said surface; and~~
a centrally located injection port in said second surface and a first array of substantially uniformly radially displaced injection ports positioned radially outwardly at said centrally located injection port; and
encapsulation between said first and second surfaces.

12 (Original). The device of claim 11 wherein said device is a display.

13 (Original). The device of claim 11 wherein one of said surfaces is a glass panel.

14 (Original). The device of claim 11 wherein said surfaces are surface mounted to one another.

15 (Original). The device of claim 11 wherein said device is an organic light emitting display device.

16 (Original). The device of claim 11 including a plurality of encapsulation injection ports extending through said first surface.

[Claim 17 (Canceled).]

18 (Currently Amended). The device of claim 11 47 including a second array of substantially uniformly displaced injection ports positioned radially outwardly with respect to said first array.

19 (Original). A method comprising:
injecting encapsulant into an electronic device at a first location; and
when the encapsulant reaches a second location spaced from said first location,
injecting encapsulant at a location proximate to said second location.

20 (Original). The method of claim 19 including coupling a first and second surface of an electronic device and injecting encapsulant between said first and second surfaces.

21 (Original). The method of claim 20 including forming a centrally located hole and forming a plurality of radially displaced holes arranged at a substantially uniform radius from said centrally located hole.

22 (Original). The method of claim 21 including injecting encapsulant through said centrally located hole until the encapsulant reaches said radially displaced holes and thereafter stopping the injection of encapsulant through said centrally located hole and injecting encapsulant through said radially displaced holes.

23 (Original). The method of claim 19 including forming an electronic display.

24 (Original). The method of claim 19 including injecting encapsulant into a region between a pair of spaced plates.

25 (Original). The method of claim 24 including injecting encapsulant through one of said plates.

26 (New). A method comprising:

forming a centrally located hole in a first surface of an electronic device;
forming a plurality of radially displaced holes arranged at substantially uniform radius from said centrally located hole in a first or a second surface;
coupling the first and second surface of an electronic device; and
injecting an encapsulant between said first and second surfaces through said centrally located hole until the encapsulant reaches said radially displaced hole and thereafter stopping the injection from encapsulant through said centrally located hole and injecting encapsulant through said radially displaced holes.

27 (New). The method of claim 26 wherein injecting encapsulant causes encapsulant front to extend outwardly from the center of a region to be encapsulated between said first and second surfaces.

28 (New). The method of claim 26 including forming an electronic display.

29 (New). The method of claim 28 including injecting an encapsulant into a region between a pair of spaced parallel plates.
